 Member of the Texas Instruments Widebus™ Family 	DL, DGG, OR DGV PACKAGE (TOP VIEW)
 Operates From 1.65 V to 3.6 V 	10E 1 48 20E
 Inputs Accept Voltages to 5.5 V 	1Y1 0 2 47 1 1A1
Max t_{pd} of 4.4 ns at 3.3 V	1Y2 🛮 3 46 🗓 1A2
 Output Ports Have Equivalent 26-Ω Series 	GND [] 4 45 [] GND
Resistors, So No External Resistors Are	1Y3 0 5 44 0 1A3
Required	1Y4 [6 43] 1A4
 Typical V_{OLP} (Output Ground Bounce) 	V _{CC} [] 7 42 [] V _{CC} 2Y1 [] 8 41 [] 2A1
<0.8 V at V_{CC} = 3.3 V, T_A = 25°C	2Y2 9 40 2A2
Typical V _{OHV} (Output V _{OH} Undershoot)	GND 10 39 GND
>2 V at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$	2Y3 🛛 11 38 🗍 2A3
I _{off} Supports Partial-Power-Down Mode	2Y4 🛛 12 37 🖟 2A4
Operation	3Y1 🛮 13 36 🖟 3A1
Supports Mixed-Mode Signal Operation on All Bosts (5 V Innut/Output Voltage With	3Y2 [14 35] 3A2
All Ports (5-V Input/Output Voltage With 3.3-V V _{CC})	GND [] 15 34 [] GND 3Y3 [] 16 33 [] 3A3
Bus Hold on Data Inputs Eliminates the	3Y4 17 32 3A4
Need for External Pullup/Pulldown	V _{CC} [18 31] V _{CC}
Resistors	4Y1 1 19 30 4A1
Latch-Up Performance Exceeds 250 mA Per	4Y2 [] 20 29] 4A2
JESD 17	GND 21 28 GND
ESD Protection Exceeds JESD 22	4Y3 [] 22 27 [] 4A3
 2000-V Human-Body Model (A114-A) 	4Y4 23 26 4A4
200-V Machine Model (A115-A)	4 0E [24 25] 3 0E
1000-V Charged-Device Model (C101)	

description/ordering information

This 16-bit buffer/driver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVCH162244A is designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. It provides true outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER		
	CCOD DI	Tube	SN74LVCH162244ADL	11/01/4000444	
4000 to 0500	SSOP – DL	Tape and reel	SN74LVCH162244ADLR	LVCH162244A	
–40°C to 85°C	TSSOP - DGG	Tape and reel	SN74LVCH162244AGR	LVCH162244A	
	TVSOP – DGV Tape and		SN74LVCH162244AVR	LN2244A	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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Widebus is a trademark of Texas Instruments.



description/ordering information (continued)

The outputs, which are designed to sink up to 12 mA, include equivalent 26- Ω resistors to reduce overshoot and undershoot.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

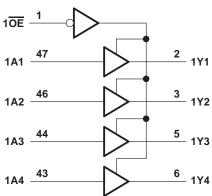
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

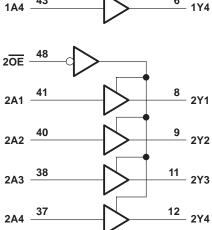
Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

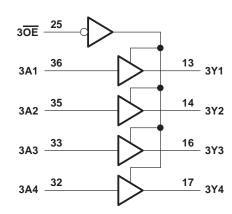
FUNCTION TABLE (each 4-bit buffer)

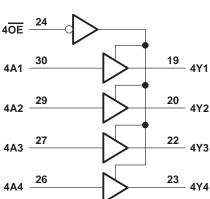
INP	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	X	Z

logic diagram (positive logic)











absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
(see Note 1)	
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, IO	
Continuous current through each V _{CC} or GND	
Package thermal impedance, θ _{JA} (see Note 3): DGG package	
DGV package	
DL package	63°C/W
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of $V_{\hbox{\scriptsize CC}}$ is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
\/	Complements	Operating	1.65	3.6	V	
VCC	Supply voltage	Data retention only	1.5		V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}			
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V			V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}		
V_{IL}	V _{IL} Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
٧ı	Input voltage		0	5.5	V	
	0	High or low state	0	Vcc	.,	
۷O	VO Output voltage	3-state	0	5.5	V	
		V _{CC} = 1.65 V		-2		
	Disk level colored comment	V _{CC} = 2.3 V		-4	mA	
ЮН	High-level output current	V _{CC} = 2.7 V		-8		
		V _{CC} = 3 V		-12		
		V _{CC} = 1.65 V		2		
	Lavorino de contracto compani	V _{CC} = 2.3 V		4	4	
lOL	Low-level output current	V _{CC} = 2.7 V		8	mA	
		V _{CC} = 3 V		12	1	
Δt/Δν	Input transition rise or fall rate	•		10	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	MIN	TYP† MAX	UNIT	
	$I_{OH} = -100 \mu\text{A}$	1.65 V to 3.6 V	V _{CC} -0.2			
^V OH	$I_{OH} = -2 \text{ mA}$	1.65 V	1.2			
	1	2.3 V	1.7			
	$I_{OH} = -4 \text{ mA}$	2.7 V	2.2		V	
	$I_{OH} = -6 \text{ mA}$	3 V	2.4			
	$I_{OH} = -8 \text{ mA}$	2.7 V	2			
	$I_{OH} = -12 \text{ mA}$	3 V	2			
	$I_{OL} = 100 \mu\text{A}$	1.65 V to 3.6 V		0.2		
	I _{OL} = 2 mA	1.65 V		0.45		
	1 4 4	2.3 V		0.7		
V _{OL}	I _{OL} = 4 mA	2.7 V		0.4	V	
~-	I _{OL} = 6 mA	3 V		0.55		
	I _{OL} = 8 mA	2.7 V		0.6		
	I _{OL} = 12 mA	3 V		0.8		
lį	V _I = 0 to 5.5 V	3.6 V		±5	μΑ	
	V _I = 0.58 V	1.65 V	‡			
	V _I = 1.07 V	1.65 V	‡			
	V _I = 0.7 V	2.3 V	45		μΑ	
l _l (hold)	V _I = 1.7 V	2.3 V	-45			
, ,	V _I = 0.8 V	3 V	75			
	V _I = 2 V	3 V	-75			
	$V_{I} = 0 \text{ to } 3.6 \text{ V}$	3.6 V		±500		
l _{off}	V_I or $V_O = 5.5 V$	0		±10	μΑ	
loz	$V_{O} = 0 \text{ to } 5.5 \text{ V}$	3.6 V		±10	μΑ	
la a	$V_I = V_{CC}$ or GND	261/		20	^	
Icc	$3.6 \text{ V} \le \text{V}_1 \le 5.5 \text{ V}_1$ $I_0 = 0$	3.6 V		20	μΑ	
ΔlCC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V		500	μΑ	
Ci	$V_I = V_{CC}$ or GND	3.3 V		5.5	pF	
Co	$V_O = V_{CC}$ or GND	3.3 V		6	pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER FROM		DARAMETER I I I I I I I I I I I I I I I I I I I		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT		
L		(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	^t pd	А	Υ	1	10.2	1	6.4	1	5.6	1.1	4.4	ns
Γ	t _{en}	ŌĒ	Υ	1	14.8	1	8.2	1	6.9	1	5.5	ns
Γ	t _{dis}	ŌĒ	Y	1	12.3	1	7.1	1	6.8	1.8	6.3	ns



[‡] This information was not available at the time of publication.

[§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

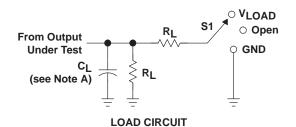
[¶] This applies in the disabled state only.

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER			V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
<u> </u>	Power dissipation capacitance	Outputs enabled	f 40 MU-	†	†	35	pF
C _{pd}	per buffer/driver	Outputs disabled	f = 10 MHz	†	†	4	рг

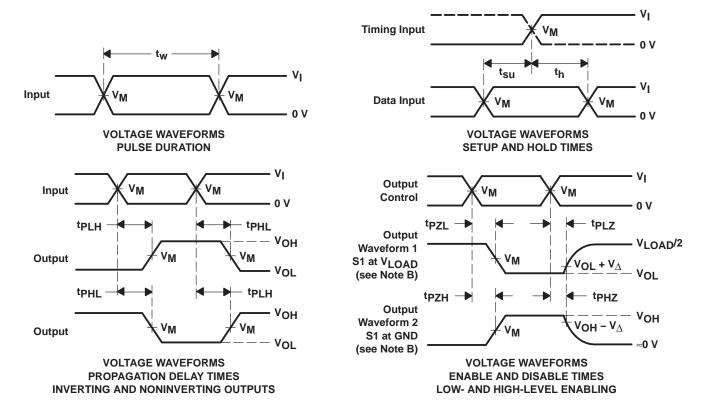
[†] This information was not available at the time of publication.

PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

INPUTS		PUTS	.,	.,		_	.,
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
1.8 V ± 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω .
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzI and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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